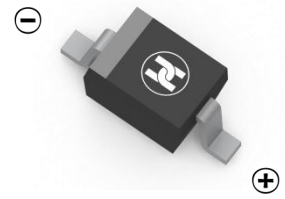
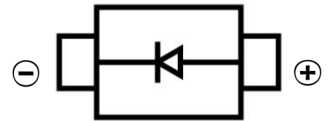


SCHOTTKY BARRIER DIODE
FEATURES

- Low Forward Voltage
- Fast Switching
- Surface Mount device
- For Low Current Rectifier Circuits Applications


SOD-323

MECHANICAL DATA

- Case: SOD-323
- Case Material: Molded Plastic. UL flammability
- Classification Rating: 94V-0
- Weight: 0.005 grams (approximate)
- Marking:86

MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	30	V
Forward Current	I _F	200	mA
Non-Repetitive Peak Forward Surge Current @ t = 10 ms	I _{FSM}	0.6	A
Power Dissipation	P _D	200	mW
Thermal Resistance From Junction To Ambient	R _{θJA}	550	°C/W
Junction Temperature	T _J	125	°C
Storage Temperature	T _{STG}	-55 ~+150	°C

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise specified)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Reverse breakdown voltage	V _{(BR)R}	30			V	I _R =0.1mA
Forward voltage	V _F			0.23	V	I _F =0.1mA
				0.30		I _F =1.0mA
				0.40		I _F =10mA
				0.5		I _F =30mA
				1.0		I _F =100mA
Reverse voltage leakage current	I _R			2	μA	V _R =25V, T _J =25°C
				100		V _R =25V, T _J =100°C
Diode capacitance	C _D			10	pF	V _R =1.0V, f=1.0MHz
Reverse recovery time	T _{rr}			5	nS	I _F =10mA, I _R =10~1mA, R _L =100Ω

SCHOTTKY BARRIER DIODE

Typical Characteristics

Fig. 1-1: Forward voltage drop versus forward current (typical values, low level).

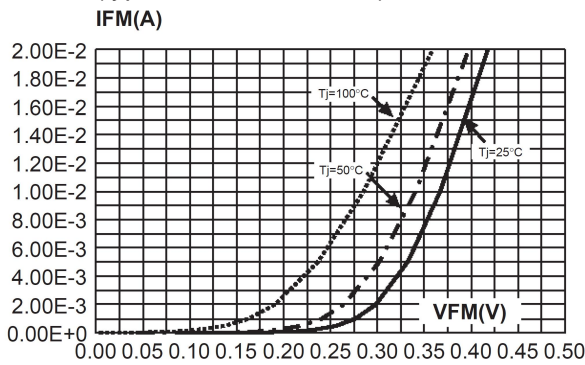


Fig. 1-2: Forward voltage drop versus forward current (typical values, high level).

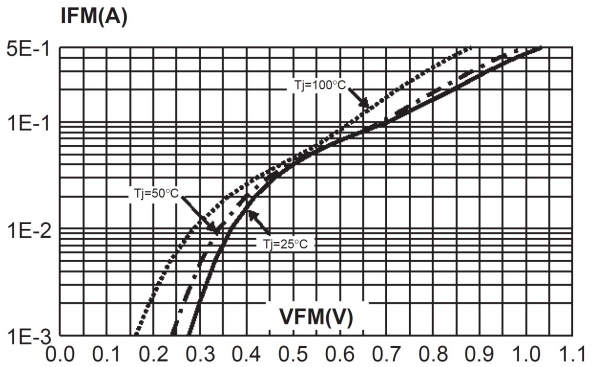


Fig. 2: Reverse leakage current versus reverse voltage applied (typical values).

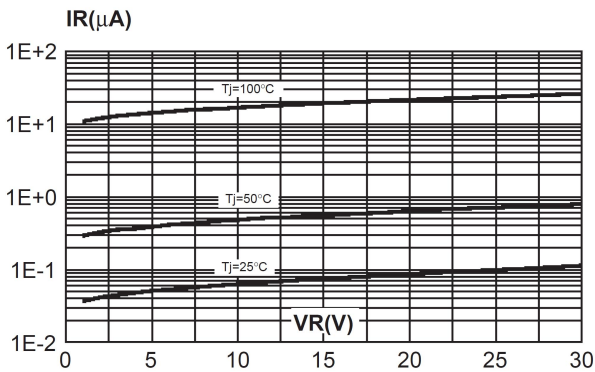


Fig. 3: Reverse leakage current versus junction temperature.

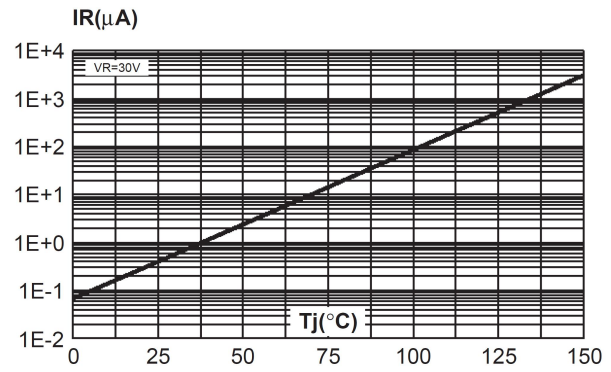


Fig. 4: Junction capacitance versus reverse voltage applied (typical values).

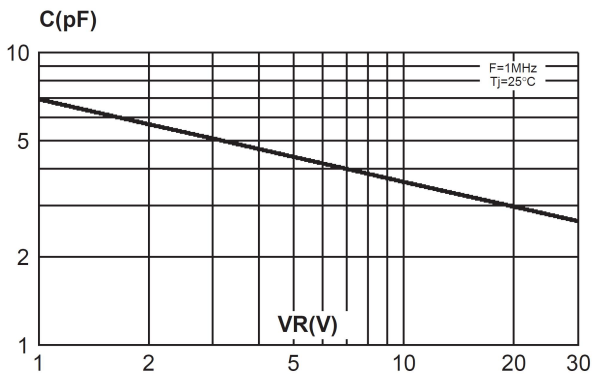


Fig. 5: Relative variation of thermal impedance junction to ambient versus pulse duration (epoxy FR4 with recommended pad layout, e(Cu)=35μm)

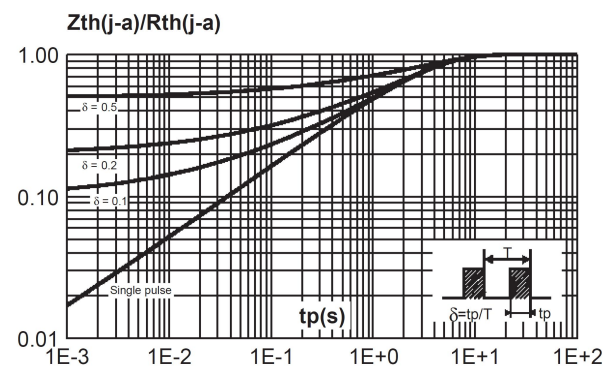
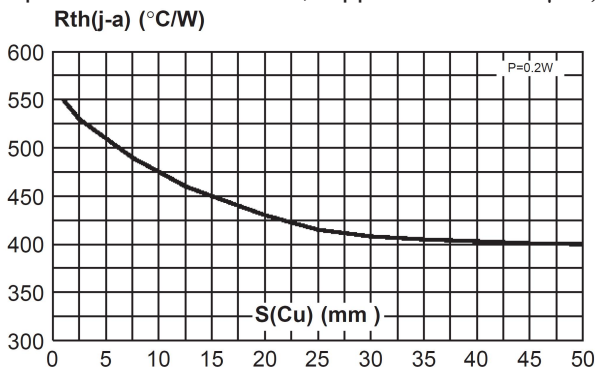
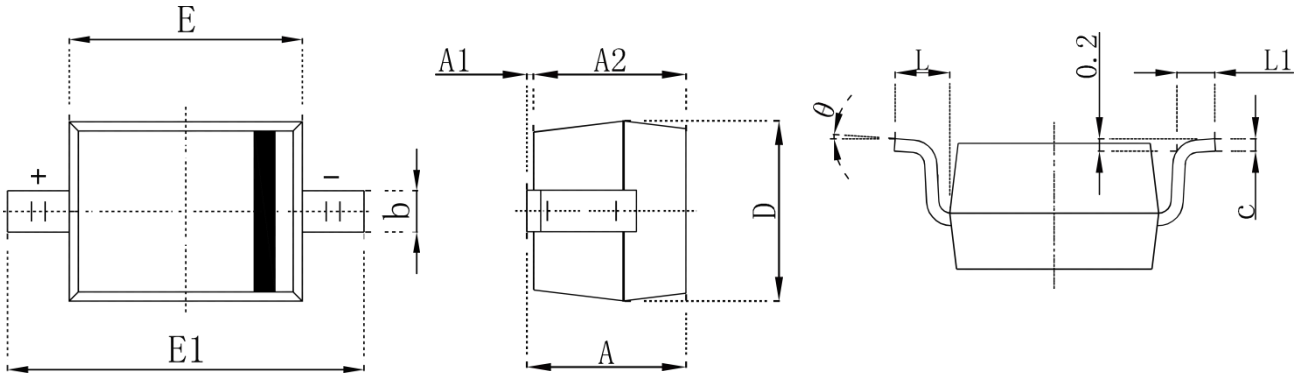


Fig. 6: Thermal resistance junction to ambient versus copper surface under each lead (Epoxy printed circuit board FR4, copper thickness: 35μm.)



SCHOTTKY BARRIER DIODE
SOD-323 Package Outline Dimensions


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A		1.000		0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.250	2.750	0.100	0.108
L	0.475 REF		0.019 REF	
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

SOD-323 Suggested Pad Layout

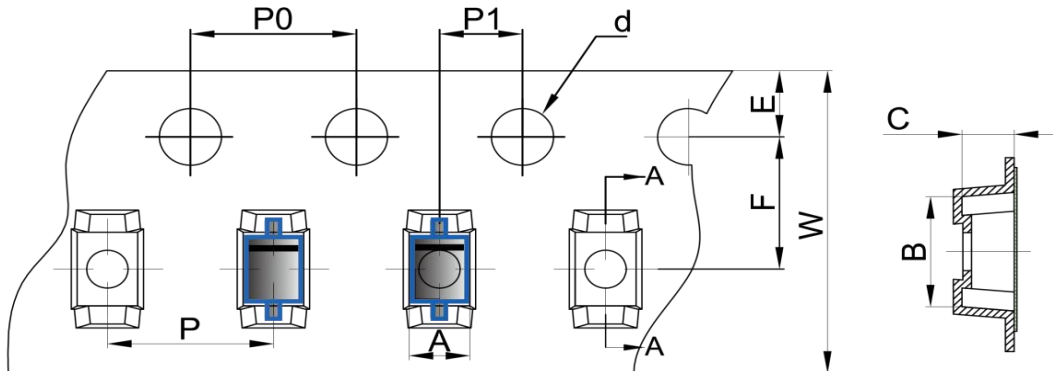
Note:

1. Controlling dimension: in millimeters
2. General tolerance: $\pm 0.05\text{mm}$
3. The pad layout is for reference purposes only

SCHOTTKY BARRIER DIODE

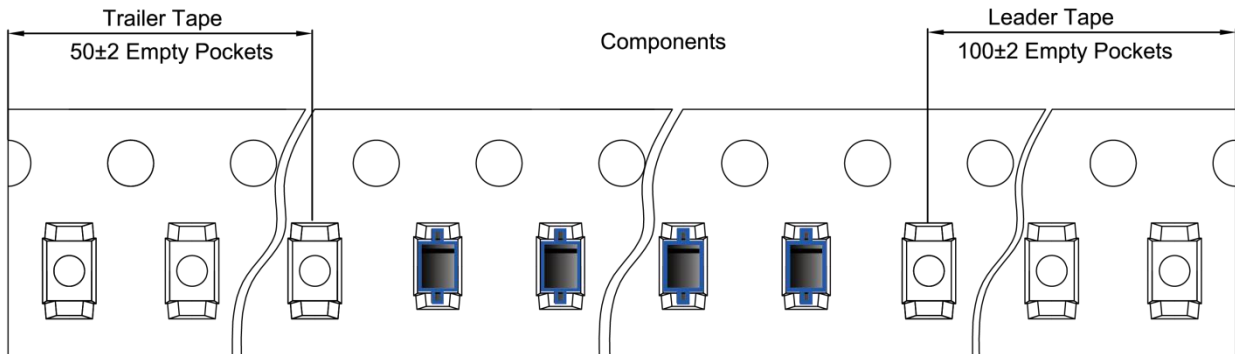
SOD-323 Tape and Reel

SOD-323 Embossed Carrier Tape

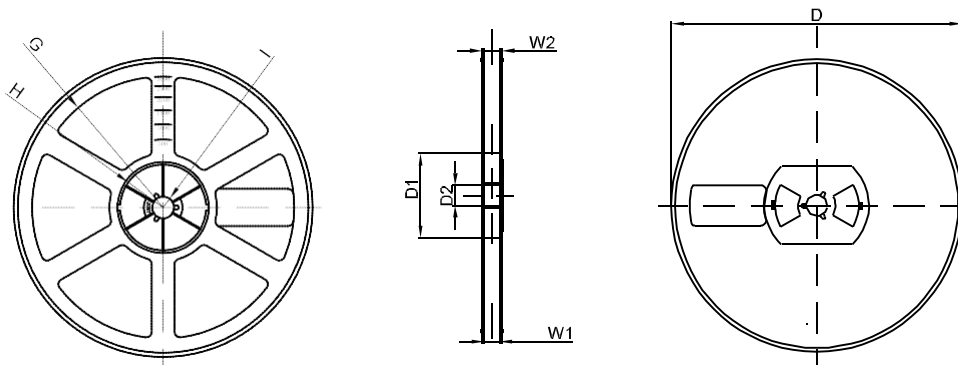


DIMENSIONS ARE IN MILLIMETER										
TYPE	A	B	C	d	E	F	P0	P	P1	W
SOD-323	1.48	3.3	1.25	Ø1.50	1.75	3.50	4.00	4.00	2.00	8
TOLERANCE	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1

SOD-323 Tape Leader and Trailer



SOD-323 Reel



DIMENSIONS ARE IN MILLIMETER								
REEL OPTION	D	D1	D2	G	H	I	W1	W2
7" DIA	Ø178	54.40	13.00	R78	R25.60	R6.50	9.50	12.30
TOLERANCE	±2	±1	±1	±1	±1	±1	±1	±1